

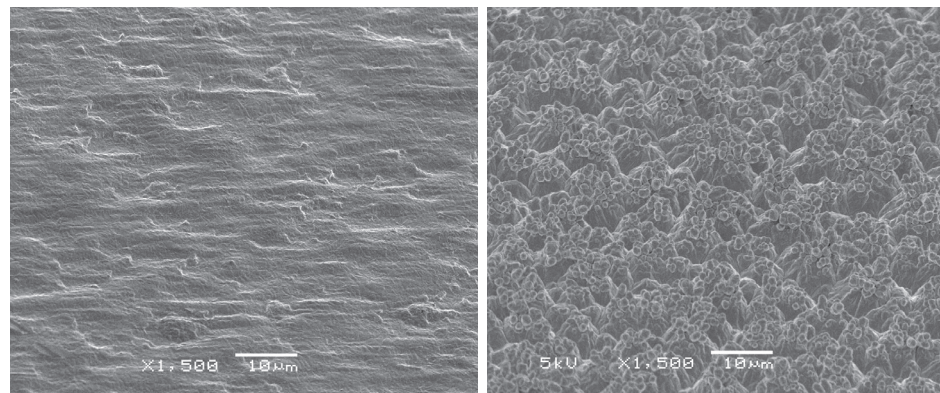
High flex electrodeposited copper foil.

### Applications:

- Flex to install PCB

### Features:

- IPC Grade II
- Treatment on matte side of foil
- Excellent adhesion to a wide range of resin systems



Untreated Drum Side  
H oz. /18 µm (1500x)

Treated Matte Side  
H oz. /18 µm (1500x)

### Typical Values:

Attribute		Unit	Value			Reference
Thickness Designation			H	1	2	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		µm	18	35	70	
		oz.	1/2	1	2	
Area Weight		g/m <sup>2</sup>	152.5	305	610	
		g/254 in <sup>2</sup>	25	50	100	
		oz./ft <sup>2</sup>	0.5	1	2	
Roughness	Drum Side Ra	µm	0.25			IPC-TM-650-2.2.17
		µ"	10			
	Matte Side Rz	µm	5.1	6.4	10.2	
		µ"	200	250	400	
Tensile	Ambient	Kg/mm <sup>2</sup>	42.2	38.7	36.9	IPC-TM-650-2.4.18
		Kpsi	60	55	52.5	
Elongation	Ambient	%	8	15	20	
Peel Strength* (Matte/Treated Side)	Cond. B	Kg/cm	1.3	1.9	2.7	IPC-TM-650-2.4.8
		Lbs/in	7.5	10.5	15.0	

\* Peel strength measured on 170°C Tg Epoxy

*Information in this document is believed to be accurate and reliable and is for informational purpose only. This data sheet does not create any warranties, expressed or implied, as to the fitness for any particular purpose or use. The Denkai America Inc. name and logo are registered trademarks of Nippon Denkai, Ltd. © 2020, Denkai America Inc. All rights reserved. Rev May 4, 2020*